

265-615



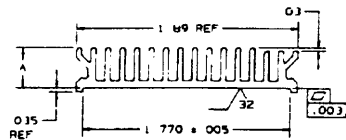
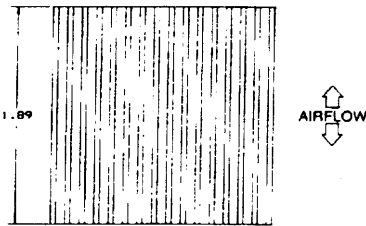
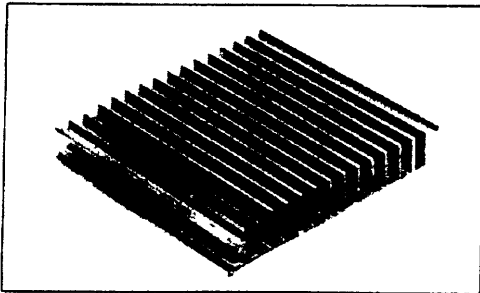
CP-clip HEAT SINKS FOR

INTEL® 486™ MICROPROCESSOR

HEAT SINKS GROUP

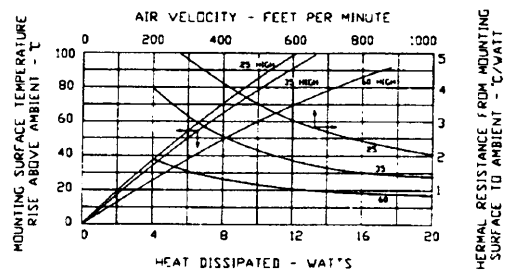
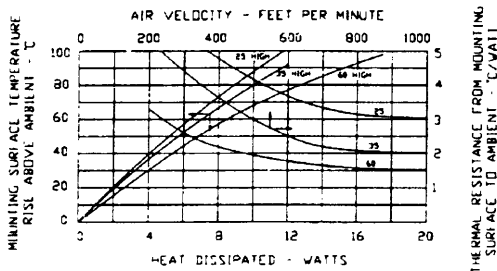
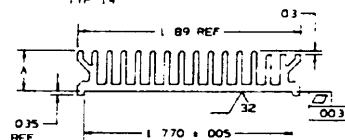
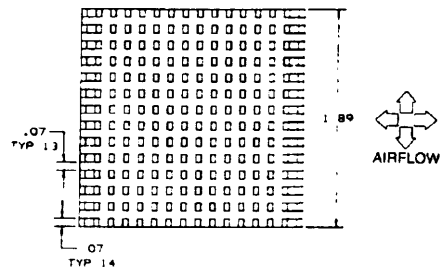
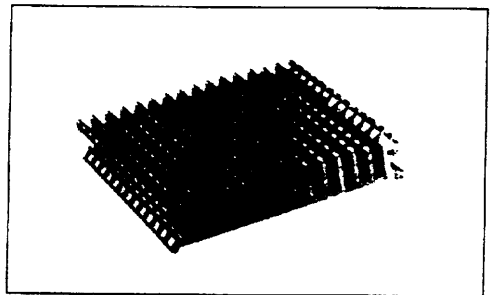
BIDIRECTIONAL HEAT SINKS

- Machined thermal interface for optimum heat transfer.
- Low cost clip-on heat sink.
- 17 x 17 PGA matrix.



OMNIDIRECTIONAL HEAT SINKS

- Flat pin design for maximum efficiency
- Utilises airflow from any direction
- Greater efficiency than bidirectional heat sinks



ORDERING INFORMATION

PART NUMBER	"A" DIM	No. FINS
CP500250B*	.250" (6.4mm)	16
CP500350B*	.350" (8.9mm)	16
CP500600B*	.600" (15.2mm)	12

ORDERING INFORMATION

PART NUMBER	"A" DIM	No. PINS
CP510250B*	.250" (6.4mm)	224
CP510350B*	.350" (8.9mm)	224
CP510600B*	.600" (15.2mm)	168

* FOR FULL ORDERING INFORMATION SEE LAST PAGE

NOTE INTEL AND 486 ARE TRADE MARKS OF INTEL CORPORATION

Thermal measurements were made by clipping each style heat sink to a 1.7" sq insulated copper block with an embedded heating element